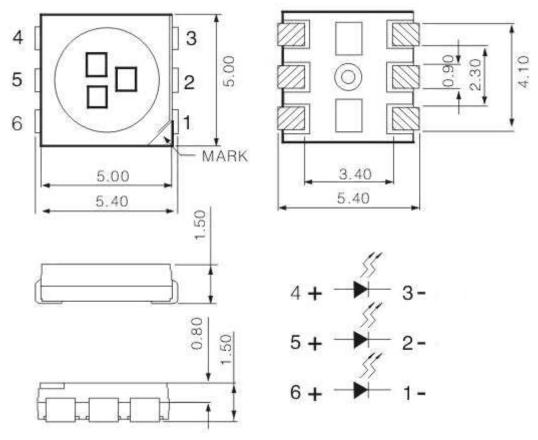
• 5mmx5mm SMD LED, 1.5mm THICKNESS.

(5 mmx5 mm SMD)

- WIDE SIDE VIEWING ANGLE.
- LOWPOWER CONSUMPTION.

Package Dimensions



- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is \pm 0.25mm (.010") unless otherwise noted.
- 3. Specifications are subject to change without notice.
- 4. This data-sheet only valid for six months.

Absolute Maximum Ratings at TA=25oC

Parameter	Maximum Rating	Unit	
Power Dissipation	200	mW	
Peak Forward Current (1/10 Duty Cycle, O.1ms Pulse width	150	mA	
Continuous Forward Current	150	mA	
Derating Linear From 50°C	0. 4	mA /℃	
Operation Temperature Range	-40°C to +80°C		
Storage Temperature Range	-40°C to +80°C		

Lead Soldering Temperature [4mm (.157") From Body]	260℃ for 5 Seconds

Electrical / Optical Characteristics at TA=25°C

Parameter	Symbol	Min.	Тур.	Max.	Unit	Test Condition
Luminous Flux	IV	15	-	17	lm	IF=60mA Note 1.4
Luminous Intensity	IV	4000		5000	mcd	IF=60mA Note 1.4
Chromaticity Coordinate (R)	CCT	2700	5000	10000	K	IF=60mA Note4
Viewing Angle	2θ 1/2		120		deg	Note 2
Forward Voltage	VF	3.0	3.3	3.6	V	IF=60mA
Reverse Current	IR	-	-	5	μА	VR=5V

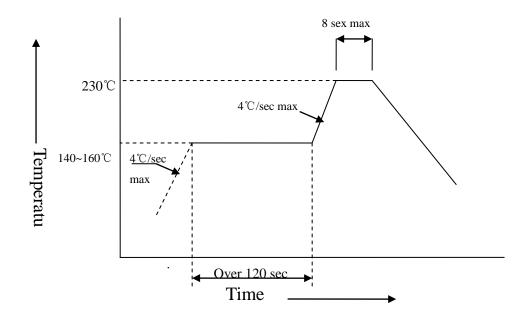
Note: 1.Luminous intensity is measured with a light sensor and filter combination that approximates the CIE (Commission International De L'Eclairage) eye-response curve.

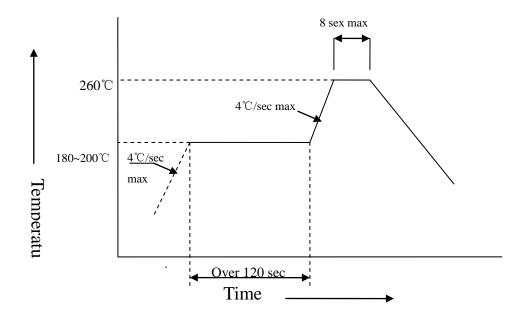
- 2.1/2 is the off-axis angle at which the luminous intensity is half the axial luminous and intensity.
- 3. The dominant wavelength, λ d is derived from the CIE chromaticity diagram and represents the single wavelength which defines the color of the device.
- 4. The IV guarantee should be added $\pm 15\%$.

Reflow Soldering Instructions

Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and Second soldering process.

1>Lead Solder





Recommended Soldering Patter

<Units:mm>

